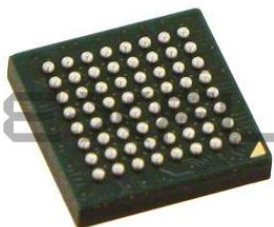


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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I ² C, IrDA, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I ² S, LVD, POR, PWM, WDT
Number of I/O	40
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 22x16b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LFBGA
Supplier Device Package	64-MAPBGA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk22fn256vmp12

Table 2. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{LVW2H}	• Level 2 falling (LVWV=01)	2.72	2.80	2.88	V	
V _{LVW3H}	• Level 3 falling (LVWV=10)	2.82	2.90	2.98	V	
V _{LVW4H}	• Level 4 falling (LVWV=11)	2.92	3.00	3.08	V	
V _{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	80	—	mV	
V _{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	
V _{LVW1L}	Low-voltage warning thresholds — low range					1
V _{LVW2L}	• Level 1 falling (LVWV=00)	1.74	1.80	1.86	V	
V _{LVW3L}	• Level 2 falling (LVWV=01)	1.84	1.90	1.96	V	
V _{LVW4L}	• Level 3 falling (LVWV=10)	1.94	2.00	2.06	V	
V _{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	60	—	mV	
V _{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	
t _{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	μs	

1. Rising threshold is the sum of falling threshold and hysteresis voltage

Table 3. VBAT power operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{POR_VBAT}	Falling VBAT supply POR detect voltage	0.8	1.1	1.5	V	

2.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{OH}	Output high voltage — Normal drive pad except RESET_B					
	2.7 V ≤ V _{DD} ≤ 3.6 V, I _{OH} = -5 mA	V _{DD} - 0.5	—	—	V	1
	1.71 V ≤ V _{DD} ≤ 2.7 V, I _{OH} = -2.5 mA	V _{DD} - 0.5	—	—	V	
V _{OH}	Output high voltage — High drive pad except RESET_B					
	2.7 V ≤ V _{DD} ≤ 3.6 V, I _{OH} = -20 mA	V _{DD} - 0.5	—	—	V	1
	1.71 V ≤ V _{DD} ≤ 2.7 V, I _{OH} = -10 mA	V _{DD} - 0.5	—	—	V	
I _{OHT}	Output high current total for all ports	—	—	100	mA	

Table continues on the next page...

Table 5. Power mode transition operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	first instruction across the operating temperature range of the chip.					
	• VLLS0 → RUN	—	—	140	μs	
	• VLLS1 → RUN	—	—	140	μs	
	• VLLS2 → RUN	—	—	80	μs	
	• VLLS3 → RUN	—	—	80	μs	
	• LLS2 → RUN	—	—	6	μs	
	• LLS3 → RUN	—	—	6	μs	
	• VLPS → RUN	—	—	5.7	μs	
	• STOP → RUN	—	—	5.7	μs	

1. Normal boot (FTFA_OPT[LPBOOT]=1)

2.2.5 Power consumption operating behaviors

The current parameters in the table below are derived from code executing a while(1) loop from flash, unless otherwise noted.

The IDD typical values represent the statistical mean at 25°C, and the IDD maximum values for RUN, WAIT, VLPR, and VLPW represent data collected at 125°C junction temperature unless otherwise noted. The maximum values represent characterized results equivalent to the mean plus three times the standard deviation (mean + 3 sigma).

Table 6. Power consumption operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I _{DDA}	Analog supply current	—	—	See note	mA	1
I _{DD_HSRUN}	High Speed Run mode current - all peripheral clocks disabled, CoreMark benchmark code executing from flash @ 1.8V	—	25.66	26.35	mA	2, 3, 4

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	@ 3.0V	—	25.75	26.44	mA	
I _{DD_HSRUN}	High Speed Run mode current - all peripheral clocks disabled, code executing from flash					
	@ 1.8V	—	23.6	24.29	mA	2
	@ 3.0V	—	23.7	24.39	mA	
I _{DD_HSRUN}	High Speed Run mode current — all peripheral clocks enabled, code executing from flash					
	@ 1.8V	—	31.9	32.59	mA	5
	@ 3.0V	—	32.0	32.69	mA	
I _{DD_RUN}	Run mode current in Compute operation — CoreMark benchmark code executing from flash					
	@ 1.8V	—	15.8	16.49	mA	3, 4, 6
	@ 3.0V	—	15.8	16.49	mA	
I _{DD_RUN}	Run mode current in Compute operation — code executing from flash					
	@ 1.8V	—	14.00	15.50	mA	6
	@ 3.0V	—	14.00	15.69	mA	
I _{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash					
	@ 1.8V	—	15.3	15.99	mA	7
	@ 3.0V	—	15.4	16.09	mA	
I _{DD_RUN}	Run mode current — all peripheral clocks enabled, code executing from flash					
	@ 1.8V	—	20.4	21.09	mA	8
	@ 3.0V					
	• @ 25°C	—	20.5	21.19	mA	
	• @ 70°C	—	20.5	21.19	mA	
	• @ 85°C	—	20.5	21.19	mA	
	• @ 105°C	—	21.4	22.09	mA	
I _{DD_RUN}	Run mode current — Compute operation, code executing from flash					
	@ 1.8V	—	14.0	14.69	mA	9
	@ 3.0V					
	• @ 25°C	—	14.0	14.69	mA	
	• @ 70°C	—	14.0	14.69	mA	
	• @ 85°C	—	14.0	14.69	mA	
	• @ 105°C	—	15.0	15.69	mA	
I _{DD_WAIT}	Wait mode high frequency current at 3.0 V — all peripheral clocks disabled	—	8.1	8.79	mA	7

Table continues on the next page...

General

3. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.
4. IEC Level Maximums: M $\leq$ 18dBmV, L $\leq$ 24dBmV, K $\leq$ 30dBmV, I $\leq$ 36dBmV, H $\leq$ 42dBmV .

2.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

- Go to nxp.com
- Perform a keyword search for “EMC design.”

2.2.8 Capacitance attributes

Table 9. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C _{IN_A}	Input capacitance: analog pins	—	7	pF
C _{IN_D}	Input capacitance: digital pins	—	7	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 10. Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
High Speed run mode					
f _{SYS}	System and core clock	—	120	MHz	
f _{BUS}	Bus clock	—	60	MHz	
Normal run mode (and High Speed run mode unless otherwise specified above)					
f _{SYS}	System and core clock	—	80	MHz	
f _{SYS_USB}	System and core clock when Full Speed USB in operation	20	—	MHz	
f _{BUS}	Bus clock	—	50	MHz	
f _{FLASH}	Flash clock	—	26.67	MHz	
f _{LPTMR}	LPTMR clock	—	25	MHz	
VLPR mode ¹					
f _{SYS}	System and core clock	—	4	MHz	

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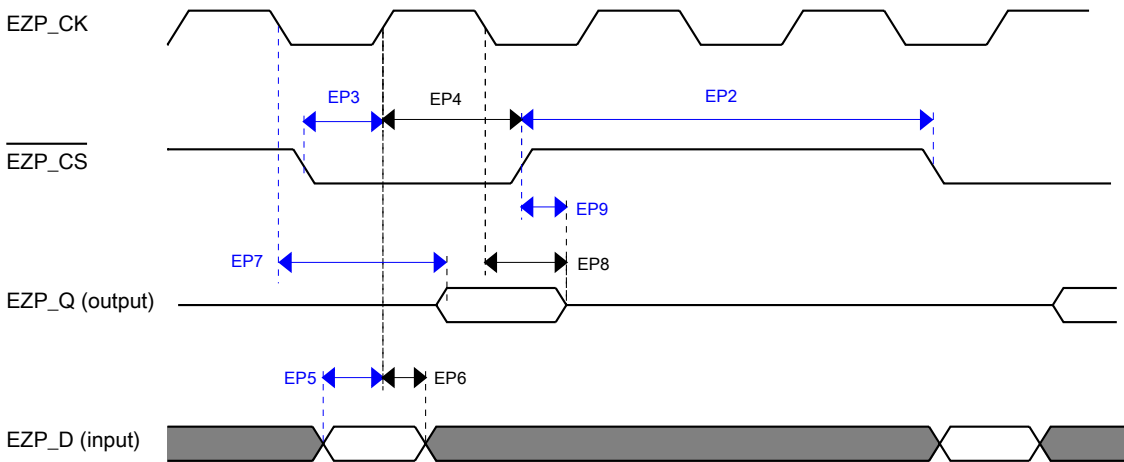


Figure 11. EzPort Timing Diagram

3.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

3.6 Analog

3.6.1 ADC electrical specifications

The 16-bit accuracy specifications listed in [Table 27](#) and [Table 28](#) are achievable on the differential pins ADCx_DPx, ADCx_DMx.

All other ADC channels meet the 13-bit differential/12-bit single-ended accuracy specifications.

3.6.1.1 16-bit ADC operating conditions

Table 27. 16-bit ADC operating conditions

Symbol	Description	Conditions	Min.	Typ. ¹	Max.	Unit	Notes
V_{DDA}	Supply voltage	Absolute	1.71	—	3.6	V	
ΔV_{DDA}	Supply voltage	Delta to V_{DD} ($V_{DD} - V_{DDA}$)	-100	0	+100	mV	2

Table continues on the next page...

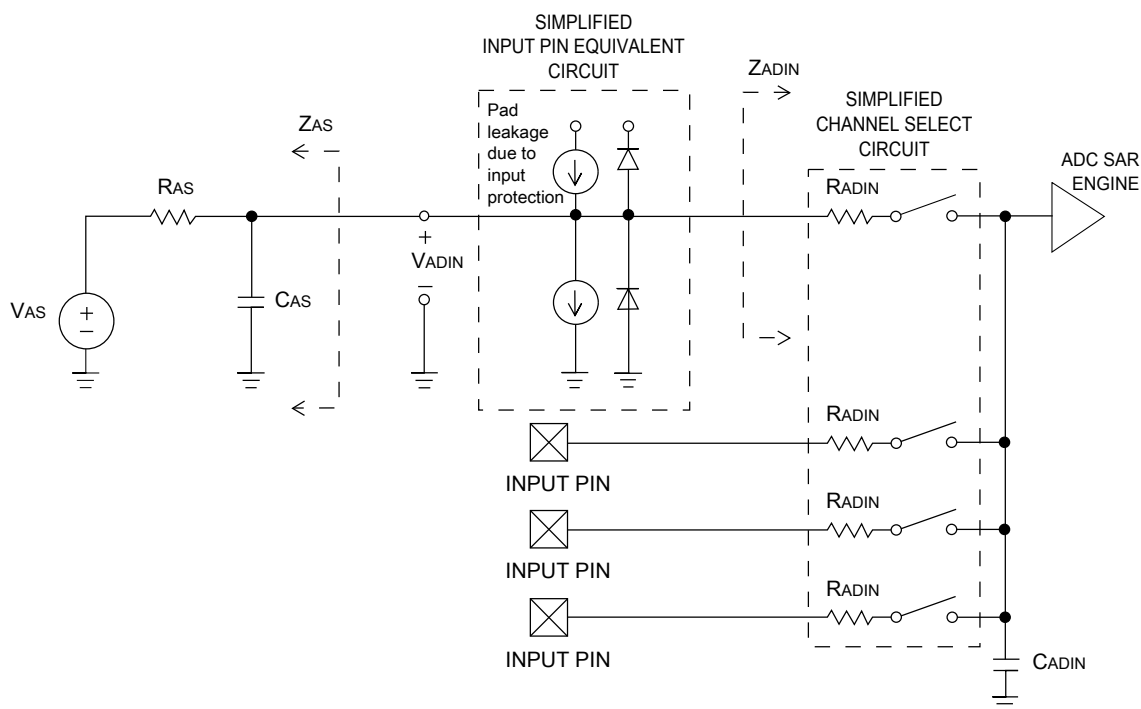


Figure 12. ADC input impedance equivalency diagram

3.6.1.2 16-bit ADC electrical characteristics

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$)

Symbol	Description	Conditions ¹	Min.	Typ. ²	Max.	Unit	Notes
I_{DDA_ADC}	Supply current		0.215	—	1.7	mA	3
f_{ADACK}	ADC asynchronous clock source	• ADLPC = 1, ADHSC = 0 • ADLPC = 1, ADHSC = 1 • ADLPC = 0, ADHSC = 0 • ADLPC = 0, ADHSC = 1	1.2 2.4 3.0 4.4	2.4 4.0 5.2 6.2	3.9 6.1 7.3 9.5	MHz MHz MHz MHz	$t_{ADACK} = 1/f_{ADACK}$
	Sample Time	See Reference Manual chapter for sample times					
TUE	Total unadjusted error	• 12-bit modes • <12-bit modes	— —	± 4 ± 1.4	± 6.8 ± 2.1	LSB ⁴	5
DNL	Differential non-linearity	• 12-bit modes • <12-bit modes	— —	± 0.7 ± 0.2	-1.1 to +1.9 -0.3 to 0.5	LSB ⁴	5
INL	Integral non-linearity	• 12-bit modes	—	± 1.0	-2.7 to +1.9	LSB ⁴	5

Table continues on the next page...

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

Symbol	Description	Conditions ¹	Min.	Typ. ²	Max.	Unit	Notes
		<12-bit modes	—	±0.5	–0.7 to +0.5		
E_{FS}	Full-scale error	12-bit modes <12-bit modes	—	–4	–5.4	LSB ⁴	$V_{ADIN} = V_{DDA}$ ⁵
E_Q	Quantization error	16-bit modes ≤13-bit modes	—	–1 to 0	—	LSB ⁴	
$ENOB$	Effective number of bits	16-bit differential mode - Avg = 32 - Avg = 4 16-bit single-ended mode - Avg = 32 - Avg = 4	12.8 11.9	14.5 13.8	— —	bits bits	6
						bits	
						bits	
						bits	
$SINAD$	Signal-to-noise plus distortion	See ENOB	$6.02 \times ENOB + 1.76$			dB	
THD	Total harmonic distortion	16-bit differential mode - Avg = 32 16-bit single-ended mode - Avg = 32	—	–94	—	dB	7
			—	–85	—	dB	
$SFDR$	Spurious free dynamic range	16-bit differential mode - Avg = 32 16-bit single-ended mode - Avg = 32	82	95	—	dB	7
			78	90	—	dB	
E_{IL}	Input leakage error		$I_{in} \times R_{AS}$			mV	I_{in} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	8
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	8

1. All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$
2. Typical values assume $V_{DDA} = 3.0$ V, Temp = 25 °C, $f_{ADCK} = 2.0$ MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.

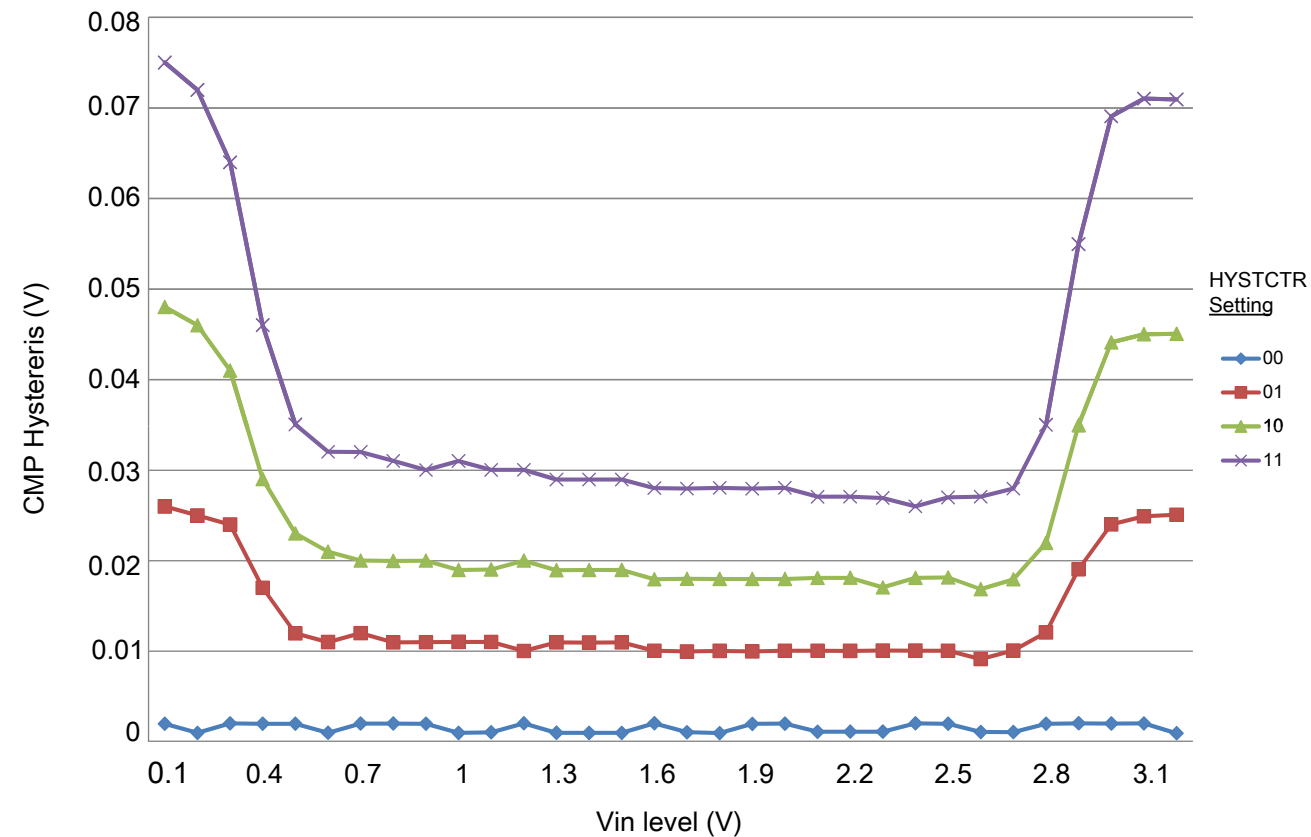


Figure 15. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)

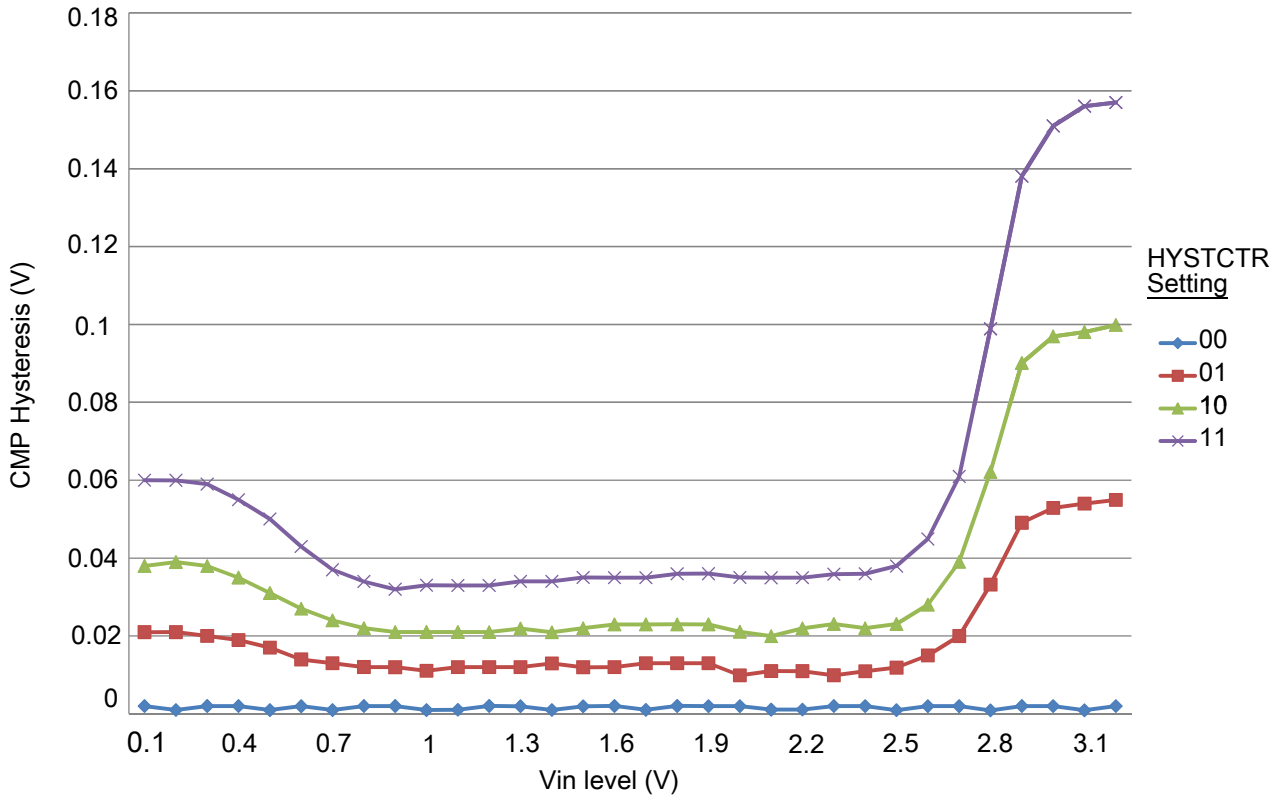


Figure 16. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)

3.6.3 12-bit DAC electrical characteristics

3.6.3.1 12-bit DAC operating requirements

Table 30. 12-bit DAC operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	
V_{DACR}	Reference voltage	1.13	3.6	V	1
C_L	Output load capacitance	—	100	pF	2
I_L	Output load current	—	1	mA	

1. The DAC reference can be selected to be V_{DDA} or V_{REFH} .
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC.

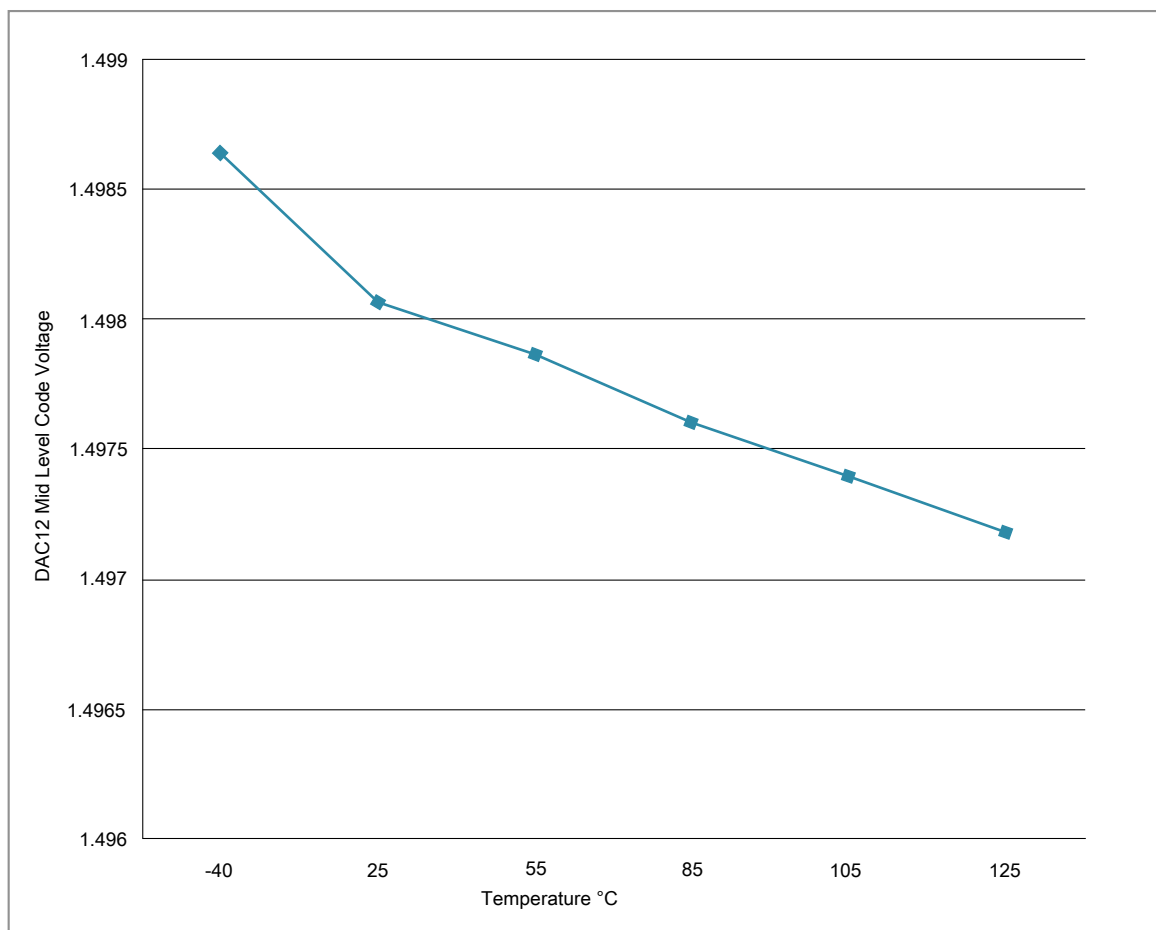


Figure 18. Offset at half scale vs. temperature

3.6.4 Voltage reference electrical specifications

Table 32. VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	
T_A	Temperature	Operating temperature range of the device		°C	
C_L	Output load capacitance	100		nF	1, 2

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.
2. The load capacitance should not exceed +/-25% of the nominal specified C_L value over the operating temperature range of the device.

3.8.1 USB electrical specifications

The USB electricals for the USB On-the-Go module conform to the standards documented by the Universal Serial Bus Implementers Forum. For the most up-to-date standards, visit usb.org.

NOTE

The MCGPLLCLK meets the USB jitter and signaling rate specifications for certification with the use of an external clock/crystal for both Device and Host modes.

The MCGFLLCLK does not meet the USB jitter or signaling rate specifications for certification.

The IRC48M meets the USB jitter and signaling rate specifications for certification in Device mode when the USB clock recovery mode is enabled. It does not meet the USB signaling rate specifications for certification in Host mode operation.

3.8.2 USB VREG electrical specifications

Table 36. USB VREG electrical specifications

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
VREGIN	Input supply voltage	2.7	—	5.5	V	
I _{DDon}	Quiescent current — Run mode, load current equal zero, input supply (VREGIN) > 3.6 V	—	125	186	μA	
I _{DDstby}	Quiescent current — Standby mode, load current equal zero	—	1.1	10	μA	
I _{DDoff}	Quiescent current — Shutdown mode - VREGIN = 5.0 V and temperature=25 °C - Across operating voltage and temperature	—	650	—	nA	
		—	—	4	μA	
I _{LOADrun}	Maximum load current — Run mode	—	—	120	mA	
I _{LOADstby}	Maximum load current — Standby mode	—	—	1	mA	
V _{Reg33out}	Regulator output voltage — Input supply (VREGIN) > 3.6 V - Run mode - Standby mode	3	3.3	3.6	V	
		2.1	2.8	3.6	V	

Table continues on the next page...

**Table 36. USB VREG electrical specifications
(continued)**

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
V _{Reg33out}	Regulator output voltage — Input supply (VREGIN) < 3.6 V, pass-through mode	2.1	—	3.6	V	2
C _{OUT}	External output capacitor	1.76	2.2	8.16	μF	
ESR	External output capacitor equivalent series resistance	1	—	100	mΩ	
I _{LIM}	Short circuit current	—	290	—	mA	

1. Typical values assume VREGIN = 5.0 V, Temp = 25 °C unless otherwise stated.

2. Operating in pass-through mode: regulator output voltage equal to the input voltage minus a drop proportional to I_{Load}.

3.8.3 DSPI switching specifications (limited voltage range)

The Deserial Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the SPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 37. Master mode DSPI timing (limited voltage range)

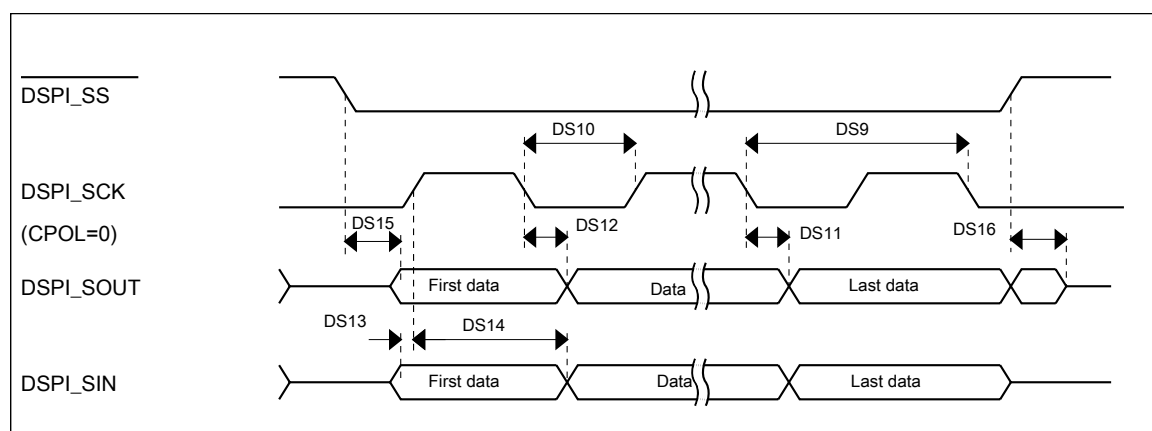
Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	30	MHz	
DS1	DSPI_SCK output cycle time	2 × t _{BUS}	—	ns	
DS2	DSPI_SCK output high/low time	(t _{SCK} /2) – 2	(t _{SCK} /2) + 2	ns	
DS3	DSPI_PCS _n valid to DSPI_SCK delay	(t _{BUS} × 2) – 2	—	ns	1
DS4	DSPI_SCK to DSPI_PCS _n invalid delay	(t _{BUS} × 2) – 2	—	ns	2
DS5	DSPI_SCK to DSPI_SOUT valid	—	8.5	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-2	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	16.2	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

1. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].

2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

Table 40. Slave mode DSPI timing (full voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	7.5	MHz
DS9	DSPI_SCK input cycle time	$8 \times t_{\text{BUS}}$	—	ns
DS10	DSPI_SCK input high/low time	$(t_{\text{SCK}}/2) - 4$	$(t_{\text{SCK}}/2) + 4$	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	29.5	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	3.2	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	DSPI_SS active to DSPI_SOUT driven	—	25	ns </td
DS16	DSPI_SS inactive to DSPI_SOUT not driven	—	25	ns

**Figure 22. DSPI classic SPI timing — slave mode**

3.8.5 Inter-Integrated Circuit Interface (I²C) timing

Table 41. I²C timing

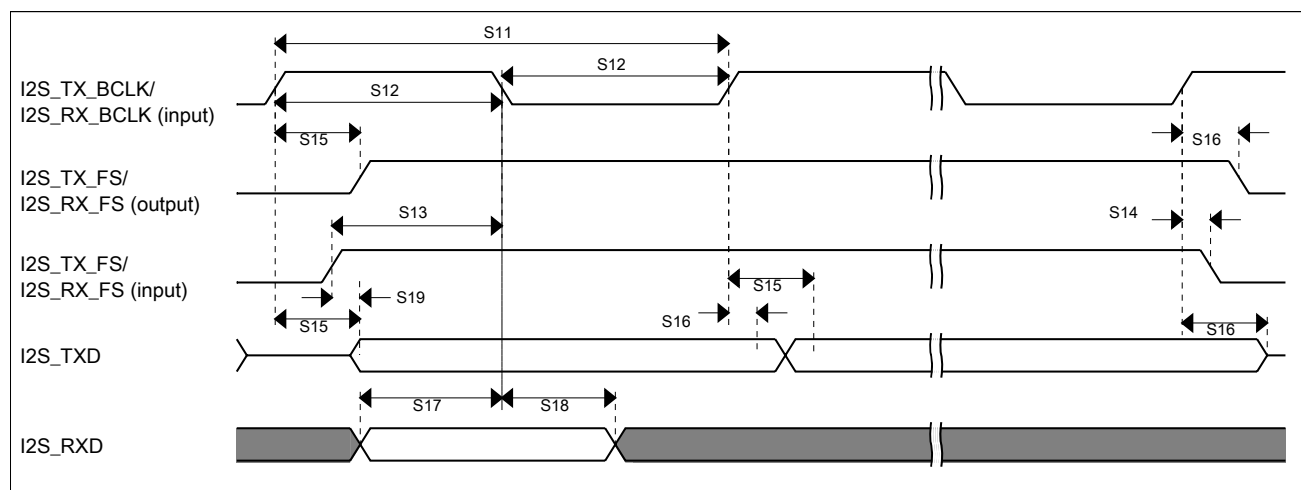
Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Minimum	Maximum	Minimum	Maximum	
SCL Clock Frequency	f_{SCL}	0	100	0	400 ¹	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD} ; STA	4	—	0.6	—	μs
LOW period of the SCL clock	t_{LOW}	4.7	—	1.25	—	μs
HIGH period of the SCL clock	t_{HIGH}	4	—	0.6	—	μs
Set-up time for a repeated START condition	t_{SU} ; STA	4.7	—	0.6	—	μs

Table continues on the next page...

Table 46. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S14	I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK	2	—	ns
S15	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid	—	28.5	ns
S16	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid	0	—	ns
S17	I2S_RXD setup before I2S_RX_BCLK	5.8	—	ns
S18	I2S_RXD hold after I2S_RX_BCLK	2	—	ns
S19	I2S_TX_FS input assertion to I2S_TXD output valid ¹	—	26.3	ns

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

**Figure 27. I2S/SAI timing — slave modes**

3.8.7.3 VLPR, VLPW, and VLPS mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in VLPR, VLPW, and VLPS modes.

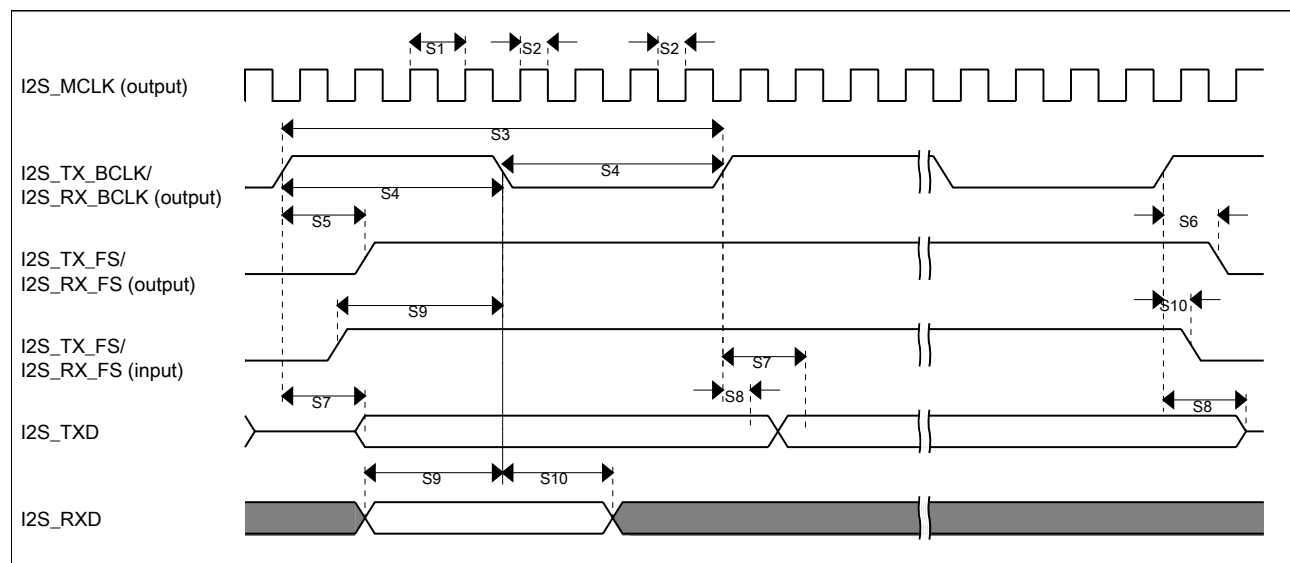
Table 47. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range)

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S1	I2S_MCLK cycle time	62.5	—	ns
S2	I2S_MCLK pulse width high/low	45%	55%	MCLK period
S3	I2S_TX_BCLK/I2S_RX_BCLK cycle time (output)	250	—	ns

Table continues on the next page...

Table 47. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S4	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid	—	45	ns
S6	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid	-1	—	ns
S7	I2S_TX_BCLK to I2S_TXD valid	—	45	ns
S8	I2S_TX_BCLK to I2S_TXD invalid	0	—	ns
S9	I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK	45	—	ns
S10	I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK	0	—	ns

**Figure 28. I2S/SAI timing — master modes****Table 48. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range)**

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S11	I2S_TX_BCLK/I2S_RX_BCLK cycle time (input)	250	—	ns
S12	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input)	45%	55%	MCLK period
S13	I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK	30	—	ns
S14	I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK	7	—	ns
S15	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid	—	63	ns

Table continues on the next page...

Pinout

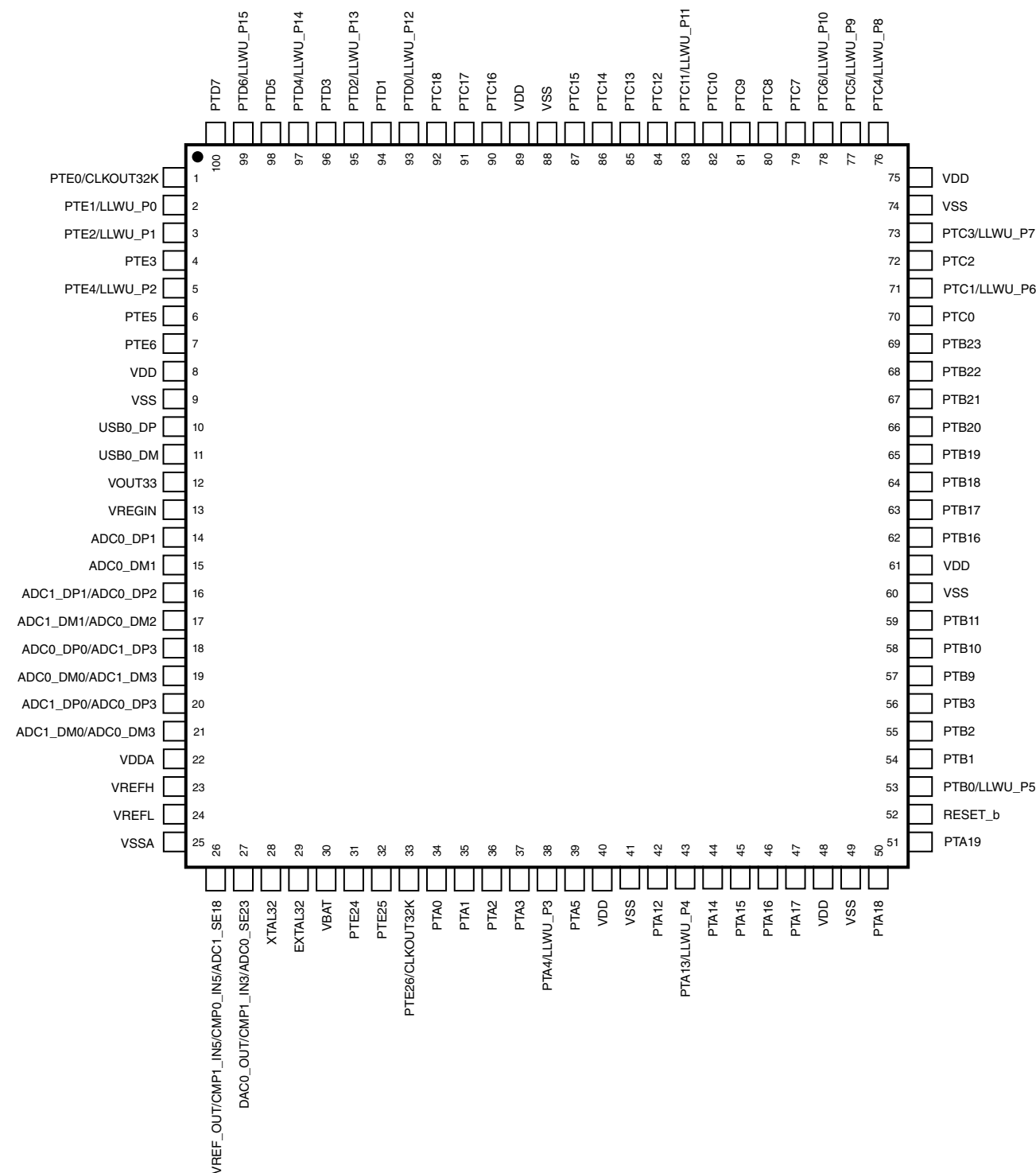


Figure 32. K22F 100 LQFP Pinout Diagram (top view)

6.2 Format

Part numbers for this device have the following format:

Q K## A M FFF R T PP CC N

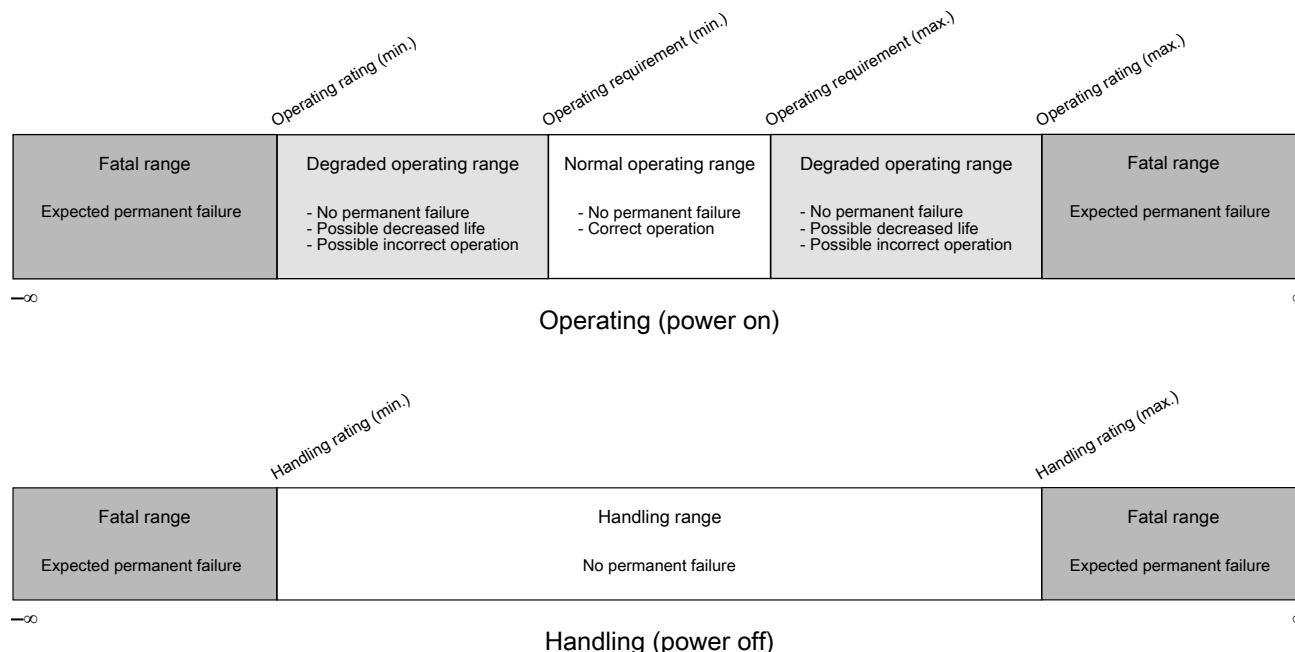
6.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
Q	Qualification status	- M = Fully qualified, general market flow, full reel - P = Prequalification - K = Fully qualified, general market flow, 100 piece reel
K##	Kinetis family	K22
A	Key attribute	- D = Cortex-M4 w/ DSP - F = Cortex-M4 w/ DSP and FPU
M	Flash memory type	- N = Program flash only - X = Program flash and FlexMemory
FFF	Program flash memory size	128 = 128 KB 256 = 256 KB 512 = 512 KB
R	Silicon revision	- Z = Initial (Blank) = Main - A = Revision after main
T	Temperature range (°C)	- V = -40 to 105 - C = -40 to 85
PP	Package identifier	- LH = 64 LQFP (10 mm x 10 mm) - MP = 64 MAPBGA (5 mm x 5 mm) - LL = 100 LQFP (14 mm x 14 mm) - MC = 121 XFBGA (8 mm x 8 mm) - DC = 121 XFBGA (8 mm x 8 mm x 0.5 mm)
CC	Maximum CPU frequency (MHz)	5 = 50 MHz 7 = 72 MHz 10 = 100 MHz 12 = 120 MHz 15 = 150 MHz
N	Packaging type	R = Tape and reel

Symbol	Description	Value	Unit
T _A	Ambient temperature	25	°C
V _{DD}	Supply voltage	3.3	V

7.4 Relationship between ratings and operating requirements



7.5 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

8 Revision History

The following table provides a revision history for this document.

Table 52. Revision History (continued)

Rev. No.	Date	Substantial Changes
		bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and $VDD \geq 2.7\text{ V}$." - Updated minimum Fast mode value for LOW period of the SCL clock to $1.25\text{ }\mu$ - Added "I²C 1 Mbps timing" table - Specified that the figure, "K22F 64 LQFP Pinout Diagram" is a top view - Specified that the figure, "K22F 64 MAPBGA Pinout Diagram" is a transparent top view - Specified that the figure, "K22F 100 LQFP Pinout Diagram" is a top view - Removed Section 6, "Ordering parts." - Corrected part marking shown in "64-pin MAPBGA part marking" table
4	7/2014	- In "Power consumption operating behaviors table": - Updated existing typical power measurements - Added new typical power measurements for the following: - IDD_HSRUN (High Speed Run mode current executing CoreMark code) - IDD_RUNCO (Run mode current in Compute operation, executing CoreMark code) - IDD_RUN (Run mode current in Compute operation, executing while(1) loop) - IDD_VLPR (Very Low Power mode current executing CoreMark code) - IDD_VLPR (Very Low Power Run mode current in Compute operation, executing while(1) loop) - In "Thermal attributes" table, added values for 64-pin MAPBGA package.
3	7/2014	- On p. 1: - Updated introduction - Under "Memories and memory interfaces," added bullet, "Pre-programmed Kinetis flashloader for one-time, in-system factory programming" - Under "Security and integrity modules," added bullet, "Hardware random-number generator" - In "Voltage and current operating ratings" table, updated maximum digital supply current - Updated "Voltage and current operating behaviors" table - Updated "Power mode transition operating behaviors" table - Updated "Power consumption operating behaviors" table - Updated figure, "Run Mode Current vs Core Frequency" - Updated figure, "Very Low Power Run (VLPR) Current vs Core Frequency" - Updated "EMC radiated emissions operating behaviors for 64 LQFP package" table - Updated "Thermal attributes" table - Updated "MCG specifications" table - Updated "IRC48M specifications" table - Updated "16-bit ADC operating conditions" table - Updated "Voltage reference electrical specifications" section - Added "121-pin XFBGA part marking" table - Added "64-pin MAPBGA part marking" table
2	3/2014	Initial public release

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